## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L2	16	((solder\$3 or braz\$3)same (bond with (stage or station or platform or bench or spot or head or tool)) same ((load or workpiece or speciment or substrate or wafer or work or semiconductor or component) with (transfer\$3 or transport\$5 or conveyor or carrier or carriage or drive)) same (computer or control or controller or controllable or manipulat\$5 or robot or robotic))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06
L4	449	228/8.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06
L5	468	228/9.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06
L6	642	228/102.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06

## **EAST Search History**

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L7	1319	228/180.22.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06		
L8	227	228/231.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06		
L9	273	228/232.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06		
L10	328	228/220.ccls.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06		
L11	3393	L4 or L5 or L6 or L7 or L8 or L9 or L10	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:06		

## **EAST Search History**

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L12	2	L11 and ((solder\$3 or braz\$3)same (bond with (stage or station or platform or bench or spot or head or tool)) same ((load or workpiece or speciment or substrate or wafer or work or semiconductor or component) with (transfer\$3 or transport\$5 or conveyor or carrier or carriage or drive)) same (computer or controll or controller or controllable or manipulat\$5 or robot or robotic))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:08
L13	31	L11 and ((solder\$3 or braz\$3)and (bond with (stage or station or platform or bench or spot or head or tool)) and ((load or workpiece or speciment or substrate or wafer or work or semiconductor or component) with (transfer\$3 or transport\$5 or conveyor or carrier or carriage or drive)) and (computer or controll or controller or controllable or manipulat\$5 or robot or robotic))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:10
L14	20	L11 and ((solder\$3 or braz\$3 or bump\$3) same (temperature same (control or control\$4 or controllable or controllably)) same (warpag\$3 or crack\$3 or warp\$3 or bulg\$3 or buckl\$3))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/08/04 19:15

8/4/2007 7:16:39 PM
C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10761412 bump forming apparatus on wafer utilizing post heat